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The technical content of this austriamicrosystems datasheet is still valid.

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AS3501 AS3502

Data Sheet

Low Power Ambient Noise-Cancelling Speaker Driver

1 General Description

The AS3501/02 are speaker driver with Ambient Noise Cancelling function for headsets, headphones or ear pieces. It is intended to improve quality of e.g. music listening, a phone conversation etc. by reducing background ambient noise.

The fully analog implementation allows the lowest power consumption, lowest system BOM cost and most natural received voice enhancement otherwise difficult to achieve with DSP implementations. The device is designed to be easily applied to existing architectures.

An internal OTP-ROM can be optionally used to store the microphones gain calibration settings.

The AS3501/02 can be used in different configurations for best trade-off of noise cancellation, required filtering functions and mechanical designs.

The simpler feed-forward topology is used to effectively reduce low frequency background noise. The feed-back topology with either 1 or 2 filtering stages can be used to reduce noise for a larger frequency range, and to even implement transfer functions like speaker equalization, Baxandall equalization, high/low shelving filter and to set a predefined loop bandwidth.

The filter loop is optimized by the user for specific headset electrical and mechanical designs by dimensioning simple R, C components.

Most headset implementations will make use of a single noise detecting microphone. Two microphones could be used to allow for increased flexibility of their location in the headset mechanical design. Using the bridged mode allows to even drive high impedance headsets.

2 Key Features

Microphone Input

- 128 gain steps @0.375dB and MUTE with AGC
- differential, low noise microphone amplifier
- single ended or differential mode
- supply for electret microphone
- MIC gain OTP programmable

High Efficiency Headphone Amplifier

- 2x34mW, 0.1% THD @ 16Ω, 1.5V supply, 100dB SNR
- bridged mode for e.g. 300Ω loads
- click and pop less start-up and mode switching

Line Input

- volume control via serial interface or volume pin
- 64 steps @ 0.75dB and MUTE, pop-free gain setting
- single ended stereo or mono differential mode

ANC processing

- feed-forward cancellation
- feed-back cancellation with filter loop transfer function definable via simple RC components
- simple in production SW calibration
- 12-30dB noise reduction (headset dependent)
- 10-2000Hz wide frequency active noise attenuation (headset dependent)

Monitor Function

- for assisted hearing, i.e. to monitor announcements
- fixed (OTP prog.) ambient sound amplification to compensate headphone passive attenuation
- volume controlled ambient sound amplification mixed with fixed (OTP prog.) attenuation of LineIn

Incremental Functions

- ANC with or without music on the receiving path
- improved dynamic range playback
- simple and low cost single noise detection microphone implementation
- OTP ROM for automatic trimming during production

Performance Parameter

- 5/3.8mA @ 1.5V stereo/mono ANC; <1uA quiescent
- extended PSRR for 217Hz

Interfaces

- 2 wire serial control mode & volume inputs
- calibration via Line-In or 2-wire serial interface
- single cell or fixed 1.0-1.8V supply with internal CP

Package

- AS3501 QFN24 [4x4mm] 0.5mm pitch
- AS3502 QFN32 [5.x5mm] 0.5mm pitch

3 Applications

Ear pieces, Headsets, Hands-Free Kits, Mobile Phones, Voice Communicating Devices



Figure 1. AS3501 Feed Forward ANC Block Diagram

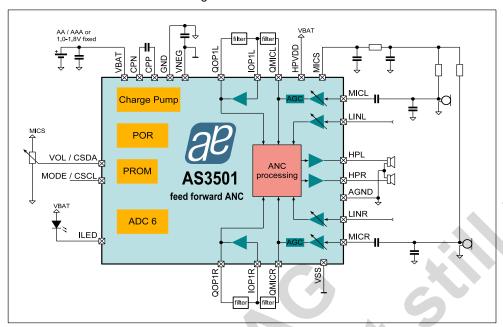
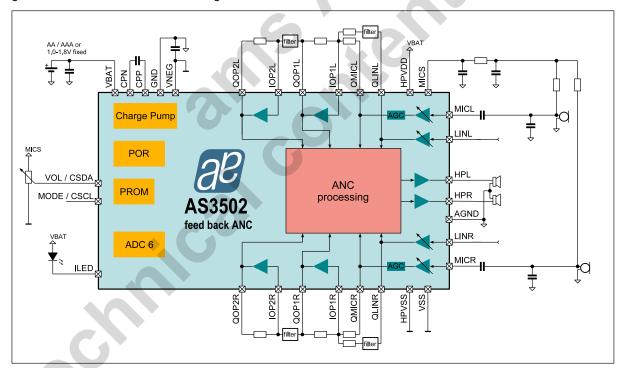


Figure 2. AS3502 Feed-Back Block Diagram





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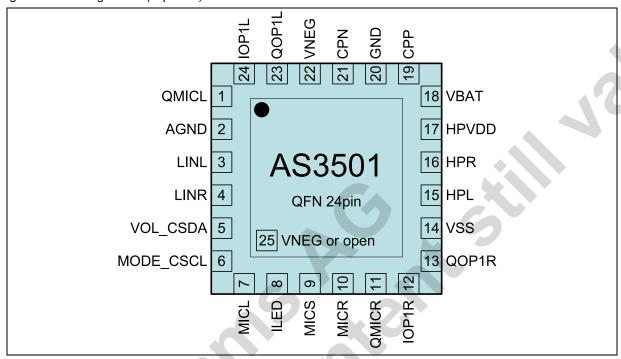


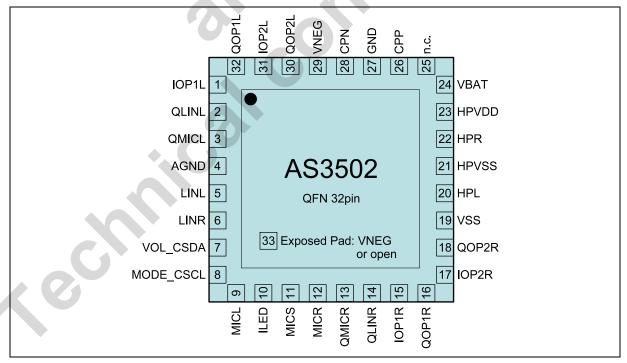
4 Pinout

4.1 Pin Assignment

Please observe that pin assignment may change in preliminary data sheets.

Figure 3. Pin Assignments (Top View)





CAUTION: Exposed pad must be connected to VNEG or left unconnected. Exposed pad must NOT be connected to GND or AGND!



4.2 Pin Description

Please observe that pin description may change in preliminary data sheets.

Table 1. Pin Description for AS3501 AS3502

A COE 04	A C2502	Din Name	Time	Description		
		Pin Name	Туре	Description		
24	1	IOP1L	ANA IN	Filter OpAmp1 Input Left Channel		
-	2	QLINL	ANA OUT	Line In Gain Stage Output Left Channel		
1	3	QMICL	ANA OUT	MIC Gain Stage Output Right Channel		
2	4	AGND	ANA IN	Analog Reference		
3	5	LINL	ANA IN DIG IN	Line In Left Channel During Application Trim Mode Write – CSDA During Application Trim Mode Burn - VNEG		
4	6	LINR	ANA IN DIG IO	LineIn Right Channel During Application Trim Mode Write – CSCL During Application Trim Mode Burn - Clock		
5	7	VOL_CSDA	MIXED IO	Serial Interface Data ADC Input for volume regulation		
6	8	MODE_CSCL	DIG IN	Mode Pin (Power Up/Down, Monitor) Serial Interface Clock		
7	9	MICL	ANA IN	Microphone In Left Channel		
8	10	ILED	ANA OUT	Current Output for on-indication LED		
9	11	MICS	ANA OUT	Microphone Supply		
10	12	MICR	ANA IN	Microphone Input Right Channel		
11	13	QMICR	ANA OUT	MIC Gain Stage Output Right Channel		
-	14	QLINR	ANA OUT	Line In Gain Stage Output Right Channel		
12	15	IOP1R	ANA IN	FilterOpAmp1 Input Right Channel		
13	16	QOP1R	ANA IN	Filter OpAmp1 Output Right Channel		
-	17	IOP2R	ANA IN	Filter OpAmp2 Input Right Channel		
-	18	QOP2R	ANA OUT	Filter OpAmp2 Output Right Channel		
14	19	VSS	SUP IN	Core and Periphery Circuit VSS Supply		
15	20	HPL	ANA OUT	Headphone Output Left Channel		
-	21	HPVSS	SUP IN	Headphone VSS Supply		
16	22	HPR	ANA OUT	Headphone Output Right Channel		
17	23	HPVDD	SUP IN	Headphone VDD Supply		
18	24	VBAT	SUP IN	VNEG ChargePump Positive Supply		
-	25	n.c.	-			
19	26	CPP	ANA OUT	VNEG ChargePump Flying Capacitor Positive Terminal		
20	27	GND	GND	VNEG ChargePump Negative Supply		
21	28	CPN	ANA OUT	VNEG ChargePump Flying Capacitor Negative Terminal		
22	29	VNEG	SUP IO	VNEG ChargePump Output		
-	30	QOP2L	ANA OUT	Filter OpAmp2 Output Left Channel		
-	31	IOP2L	ANA IN	Filter OpAmp2 Input Left Channel		
23	32	QOP1L	ANA OUT	Filter OpAmp1 Output Right Channel		
25	33			Exposed Pad: connect to VNEG or leave it unconnected		



5 Absolute Maximum Ratings

Stresses beyond those listed in Table 2 may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in Electrical Characteristics on page 7 is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. The device should be operated under recommended operating conditions.

Table 2. Absolute Maximum Ratings

Parameter	Min	Max	Units	Comments
Reference Ground				Defined as in GND
Supply terminals	-0.5	2.0	V	Applicable for pin VBAT, HPVDD
Ground terminals	-0.5	0.5	V	Applicable for pins AGND
Negative terminals	-2.0	0.5	V	Applicable for pins VNEG, VSS, HPVSS
Voltage difference at VSS terminals	-0.5	0.5	V	Applicable for pins VSS, HPVSS
Pins with protection to VBAT	VNEG -0.5	5.0 VBAT+0.5	V	Applicable for pins CPP, CPN
Pins with protection to HPVDD	VSS -0.5	5.0 HPVDD+0.5	V	Applicable for pins LINL/R, MICL/R, ILED, HPR, HPL, QMICL/R, QLINL/R, IOPx, QOPx
other pins	VSS -0.5	5		applicable for pins MICS, VOL_CSDA, MODE_CSCL
Input Current (latch-up immunity)	-100	100	mA	Norm: JEDEC 17
Continuous Power Dissipation (T _A =	+70°C)			
Continuous Power Dissipation		200	mW	Рт ¹ for QFN16/24/32 package
Electrostatic Discharge				
Electrostatic Discharge HBM		+/-2	kV	Norm: JEDEC JESD22-A114C
Temperature Ranges and Storage Co	onditions			
Junction Temperature		+110	٥C	
Storage Temperature Range	-55	+150	٥С	
Humidity non-condensing	5	85	%	
Moisture Sensitive Level		3		Represents a max. floor life time of 168h
Package Body Temperature	0	260	C	The reflow peak soldering temperature (body temperature) specified is in accordance with IPC/JEDEC J-STD-020"Moisture/Reflow Sensitivity Classification for Non-Hermetic Solid State Surface Mount Devices".

^{1.} Depending on actual PCB layout and PCB used



6 Electrical Characteristics

VBAT = 1.0V to 1.8V, T_A = -20°C to +85°C. Typical values are at VBAT = 1.5V, T_A = +25°C, unless otherwise specified. All limits are guaranteed. The parameters with min and max values are guaranteed with production tests or SQC (Statistical Quality Control) methods.

Table 3. Electrical Characteristics

Symbol	Parameter	Condition	Min	Max	Unit
ТА	Ambient Temperature Range		-20	+85	C
Supply Vol	tages				
GND	Reference Ground		0	0	V
VBAT,	Dattany Cumply Valtage	normal operation MODE pin high	1.0	1.8	V
HPVDD	Battery Supply Voltage	two wire interface operation	1.4	1.8	V
VNEG	ChargePump Voltage		-1.8	-0.7	٧
VSS	Analog neg. Supply Voltages HPVSS, VSS, VNEG		-1.8	-0.7	V
V _{DELTA} -	Difference of Ground Supplies GND, AGND	To achieve good performance, the negative supply terminals should be connected to low impedance ground plane.	-0.1	0.1	V
V _{DELTA}	Difference of Negative Supplies VSS, VNEG, HPVSS	Charge pump output or external supply	-0.1	0.1	V
V _{DELTA} +	Difference of Positive Supplies	VBAT-HPVDD	-0.25	0.25	V
other pins					
V _{MICS}	Microphone Supply Voltage	MICS	0	3.6	V
V _{HPVDD}	pins with diode to HPVDD	MICL/R, ILED, HPR, HPL, QMICL/R, QLINL/R, IOPx, QOPx	VSS	HPVDD	V
V _{VBAT}	pins with diode to VBAT	CPP, CPN	VNEG	VBAT	V
V _{CONTROL}	Control Pins	MODE_CSCL, VOL_CSDA	VSS	3.7	V
V _{TRIM}	Line Input & Application Trim Pins	LINL, LINR	VNEG -0.5 or -1.8	HPVDD +0.5 or 1.8	V

Symbol	Parameter	Condition	Min	Тур	Max	Unit				
Block Pow	lock Power Requirements @ 1.5V VBAT									
I _{OFF}	Off mode current	MODE pin low, device switched off		1		μΑ				
I _{SYS}	Reference supply current	bias generation, oscillator, ILED current sink, ADC6		0.25		mA				
I _{LIN}	LineIn gain stage current	no signal, stereo		0.64		mA				
I _{MIC}	Mic gain stage current	no signal, stereo		2.10		mA				
IHP	Headphone stage current	no signal		1.70		mA				
I _{VNEG}	VNEG charge pump current	no load		0.25		mA				
I _{MICS}	MICS charge pump current	no load		0.06		mA				
I _{MIN}	minimal supply current	sum of all above blocks		5.00		mA				



Symbol	Parameter	Condition	Min	Тур	Max	Unit
I _{OP1}	OP1 supply current	no load		0.64		mA
I _{OP2}	OP2 supply current	no load		0.64		mA
I _{ILED}	ILED current sink current	100% duty cycle		2.50		mA
I _{MICB}	Microphone bias current	200uA per microphone via charge pump		1.30		mA



7 Typical Operating Characteristics

VBAT = +1.5V, $T_A = +25$ °C, unless otherwise specified.

Figure 4. LIN to HPH: THD+N versus Output Power

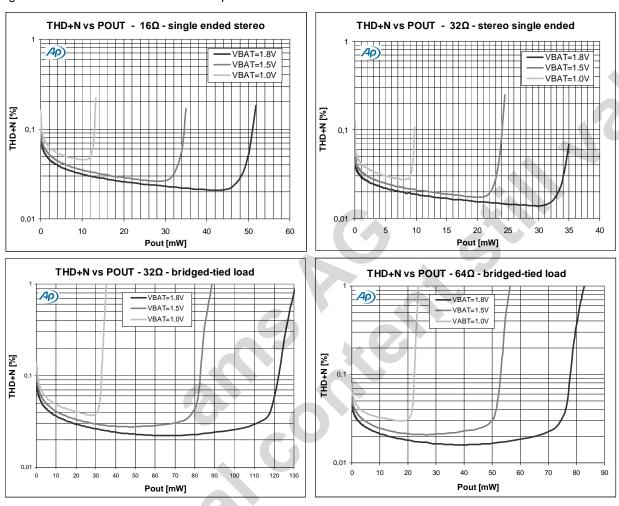
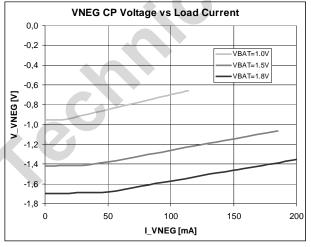
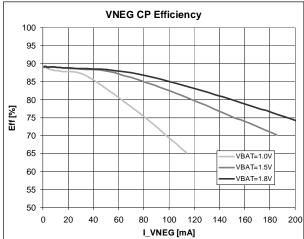


Figure 5. VNEG Charge Pump







VBAT [V]

Figure 6. Microphone Supply Generation

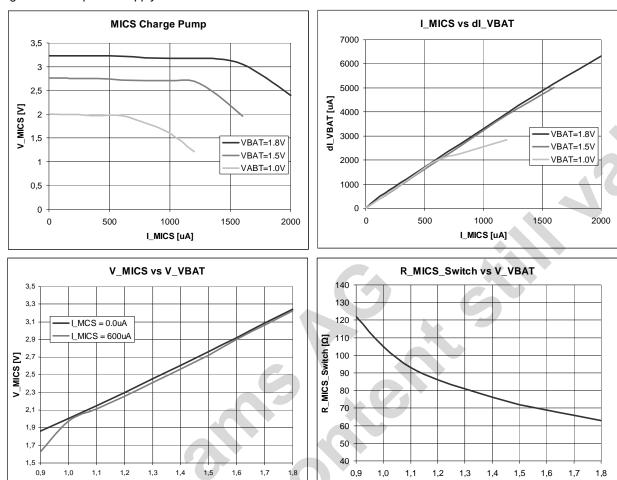


Figure 7. ILED Current Sink (100% PWM setting)

VBAT [V]

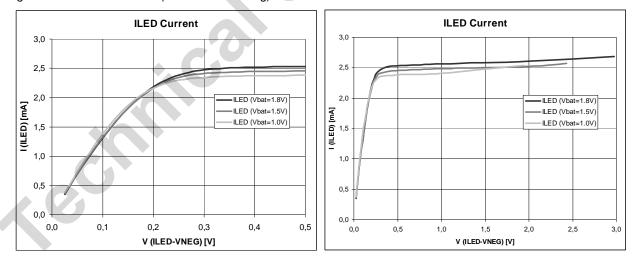




Figure 8. THD+N and Output Power(20mW) versus Frequency with 32 Ω load

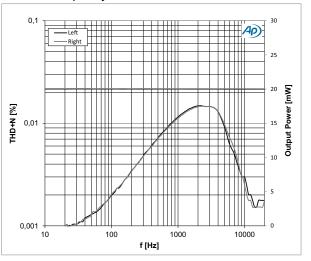


Figure 9. THD+N and Output Power(30mW) versus Frequency with 16 Ω load

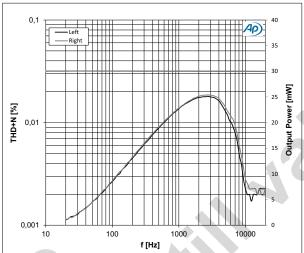


Figure 10. THD+N and Output Power(10mW) versus Frequency with 32 Ω load

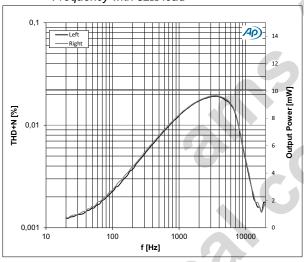


Figure 11. THD+N and Output Power(10mW) versus Frequency with 16Ω load

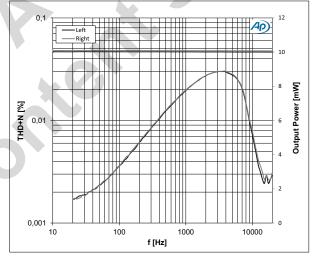


Figure 12. THD+N and Output Power(1mW) versus Frequency with 32 Ω load

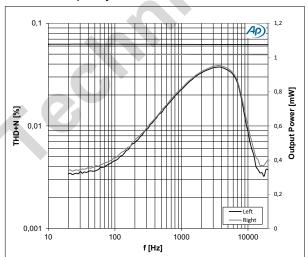


Figure 13. THD+N and Output Power(1mW) versus Frequency with 16Ω load

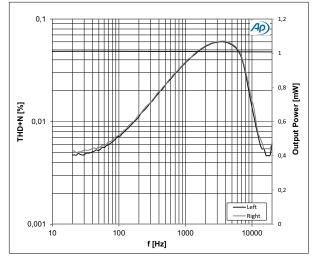


Figure 14. Typical Performance Data, FF configuration with an over the ear headset

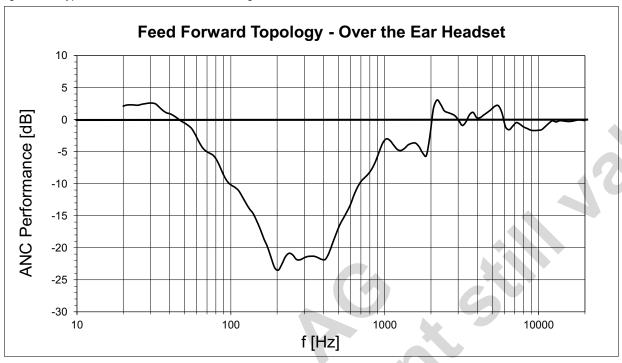
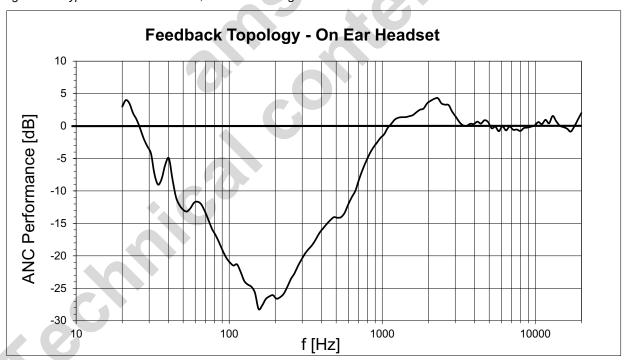


Figure 15. Typical Performance Data, Feedback configuration with an on ear headset





8 Detailed Description

8.1 Audio Line Input

8.1.1 General

The chip features one line input. The blocks can work in mono differential or in stereo single ended mode.

In addition to the $12.5-25k\Omega$ input impedance, LineIn has a termination resistor of $10k\Omega$ which is also effective during MUTE to charge eventually given input capacitors.

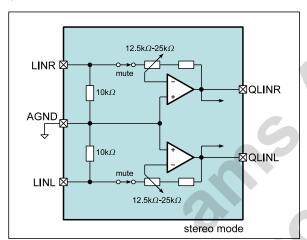
8.1.2 Gain Stage

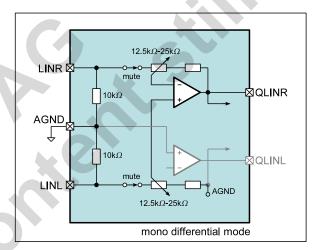
The Line In gain stage is designed to have 63 gain steps of 0.75dB with a max gain of 0dB plus MUTE.

In default, the gain will be ramped up from MUTE to 0dB during startup. There is a possibility to make the playback volume user controlled by the VOL pin with an ADC converted VOL voltage or UP/DN buttons.

In monitor mode the gain stage can be set to an fixed default attenuation level for reducing the loudness of the music.

Figure 16. Line Inputs





8.1.3 Parameter

VBAT=1.5V, T_A= 25°C, unless otherwise mentioned

Table 4. Line Input Parameter

Symbol	Parameter	Condition	Min	Тур	Max	Unit
V _{LIN}	Input Signal Level			0.6* VBAT	VBAT	V _{PEAK}
		0dB gain (12.5k // 10k)		5.6		kΩ
R _{LIN}	Input Impedance	-46.5dB gain (25k // 10k)		7.2		kΩ
		MUTE		10		kΩ
Δ_{RLIN}	Input Impedance Tolerance			±30		%
C _{LIN}	Input Capacitance			5		pF
A _{LIN}	Programmable Gain		-46.5		+0	dB
	Gain Steps	discrete logarithmic gain steps		0.75		dB
	Gain Step Accuracy			0.5		dB
A _{LINMUTE}	Mute Attenuation			100		dB



Table 4. Line Input Parameter (Continued)

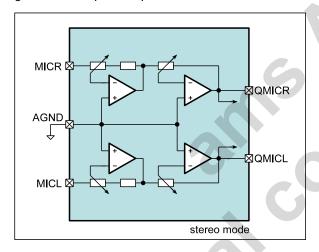
Symbol	Parameter	Condition	Min	Тур	Max	Unit
		Poti Mode, Tinit=100ms		20		
Δ_{ALIN}	Gain Ramp Rate	Button Mode, Tinit=400ms		80		ms/ step
		Monitor Mode		8		отор
V _{ATTACK}	Limiter Activation Level	HPL/R start of neg. clipping				V _{PEAK}
V _{DECAY}	Limiter Release Level	HPL/R		VNEG +0.3		V _{PEAK}
t _{ATTACK}	Limiter Attack Time			4		μs
t _{DECAY}	Limiter Decay Time			8		ms

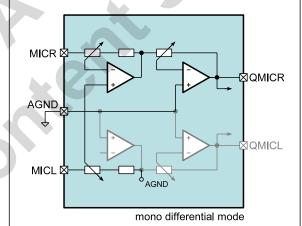
8.2 Microphone Input

8.2.1 General

The AFE offers two microphone inputs and one low noise microphone voltage supply (microphone bias). The inputs can be switched to single ended or differential mode.

Figure 17. Microphone Input





8.2.2 Gain Stage & Limiter

The Mic Gain Stage has programmable Gain within -6dB...+41.625dB in 128 steps of 0.375dB.

As soft-start function is implemented for an automatic gain ramping implemented with steps of 4ms to fade in the audio at the end of the start-up sequence.

A limiter automatically attenuates high input signals. The AGC has 127 steps with 0.375dB with a dynamic range of the full gain stage.

In monitor mode the gain stage can be set to an fixed (normally higher) gain level or be controlled by the VOL pin.

8.2.3 Supply

The MICS charge pump is providing a proper microphone supply voltage for the AAA supply. Since AAA batteries are operating down to 1.0V, the direct battery voltage cannot be used for mic-supply. There are 2 modes.

The first mode SWITCH-MODE for 1.8V supply is to have just a switch from VBAT to MICS. With this switch, the microphone current is switched off in idle mode.

The second mode CHAREGPUMP_MODE for AAA batteries is the real charge pump mode, in this mode a positive voltage is generated of about 2* VBAT.

It is also possible to switch off the microphone supply if not needed (e.g. playback without ANC)



8.2.4 Parameter

VBAT=1.5V, T_A= 25°C unless otherwise mentioned

Table 5. Microphone Input Parameter

Symbol	Parameter	Condition	Min	Тур	Max	Unit
V _{MICIN} 0	Input Signal Level	A _{MIC} = 30dB		20		mV_P
V _{MICIN} 1		A _{MIC} = 36dB		10		mV_P
V _{MICIN} 2		A _{MIC} = 42dB		5		mV_P
R _{MICIN}	Input Impedance	MICP to AGND		7.5		kΩ
Δ_{MICIN}	Input Impedance Tolerance			-7 +33		%
C _{MICIN}	Input Capacitance			5		pF
A _{MIC}	Programmable Gain		-6		+41.6	dB
	Gain Steps	discrete logarithmic gain steps		0.375		dB
	Gain Step Precision			0.15		dB
Δ_{AMIC}	Gain Ramp Rate	Tinit=64ms		4		ms/ step
VATTACK	Limiter Activation Level	V _{PEAK} related to VBAT or VNEG		0.67		1
V_{DECAY}	Limiter Release Level	VPEAK related to VBAT OF VINEG		0.4		1
AMICLIMIT	Limiter Gain Overdrive	127 @ 0.375dB		41.625		dB
tattack	Limiter Attack Time	25		5		μs/ step
t _{DECAY-DEB}	Limiter Decay Debouncing Time			64		ms
tDECAY	Limiter Decay Time			4		ms/ step
V _{MICS}	Microphone Supply Voltage			VBAT*2- 240mV		V
I _{MICSMIN}	Min. Microphone Supply Current	VBAT=+1.0V VNEG=-0.7V MICS=+1.75V		650		uA
R _{OUT_CP}	CP Output Resistance			1300		Ω

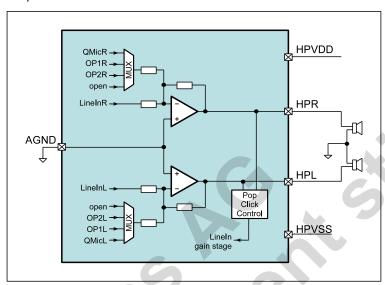


8.3 Headphone Output

8.3.1 General

The headphone output is a true ground output using VNEG as negative supply, designed to provide the audio signal with $2x12mW @ 16\Omega-64\Omega$, which are typical values for headphones. It is also capable to operate in bridged mode for higher impedance (e.g. 300Ω) headphone. In this mode the left output is carrying the inverted signal of the right output.

Figure 18. Headphone Output



8.3.2 Input Multiplexer

The signal from the line-input gain stage gets summed at the input of the headphone stage with the microphone gain stage output, the first filter opamp output or the second filter opamp output. The microphone gain stage output is used per default. It is also possible to playback without ANC by only using the line-input gain stage with no other signal on the multiplexer.

For the monitor mode the setting of this input multiplexer can be changed to an other source, normally to the microphone.

8.3.3 No-Pop Function

The No-Pop startup of the headphone stage takes 60ms to 120ms dependent on the supply voltage.

8.3.4 No-Clip Function

The headphone output stage gets monitored by comparator stages which detect if the output signal starts to clip.

This signal is used to reduce the LineIn gain to avoid distortion of the output signal. A hystereses avoids jumping between 2 gain steps for a signal with constant amplitude.

8.3.5 Over-current protection

The over-current protection has a threshold of 150-200mA and a debouncing time of 8us. The stage is forced to OFF mode in an over-current situation. After this the headphone stage tries to power up again every 8ms as long as the over-current situation still exists or the stage is turned off manually.



8.3.6 Parameter

VBAT=1.5V, T_A= 25°C, unless otherwise mentioned

Table 6. Headphone Output Parameter

Symbol	Parameter	Condition	Min	Тур	Max	Unit
R _{L_HP}	Load Impedance	stereo mode	16			Ω
C _{L_HP}	Load Capacitance	stereo mode			100	pF
P _{HP}	Nominal Output Power	RL=16Ω-64Ω	12			mW
P _{SRRHP}	Power Supply Rejection Ratio	200Hz-20kHz, 720mVpp, RL=16Ω		90		dB

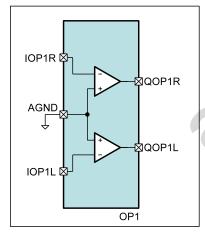
8.4 Operational Amplifier

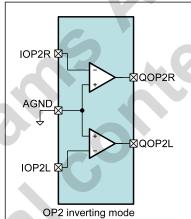
8.4.1 General

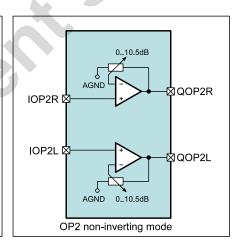
While AS3501 offers only one operational amplifiers for feed-forward ANC AS3502 feature an additional second operational amplifier stage to perform feed-back ANC or any other additional needed filtering.

Both operational amplifiers stages can be activated and used individually. While OP1 stage is always configured as inverting amplifier OP2 stage can be also switched to a non-inverting mode with an adjustable gain of 0..+10.5dB.

Figure 19. Operational Amplifiers







8.4.2 Parameter

VBAT=1.5V, T_A= 25°C, unless otherwise mentioned

Table 7. Headphone Output Parameter

Symbol	Parameter	Condition	Min	Тур	Max	Unit
R_{L_OP}	Load Impedance	single ended	1			kΩ
C _{L_OP}	Load Capacitance	single ended			100	pF
GBW _{OP}	Gain Band Width			4.3		MHz
V _{OS_OP}	Offset Voltage				6	mV
V _{EIN_HP}	Equivalent Input Noise	200Hz-20kHz		2.6		uV



8.5 SYSTEM

8.5.1 General

The system block handles the power up and power down sequencing. As well as the mode switching.

8.5.2 Power Up/Down Conditions

The chip powers up when one of the following condition is true:

Table 8. Power UP Conditions

#	Source	Description	
1	MODE pin	In stand-alone mode, MODE pin has to be driven high to turn on the device	
2	I2C start	In I2C mode, a I2C start condition turns on the device	750

The chip automatically shuts off if one of the following conditions arises:

Table 9. Power DOWN Conditions

#	Source	Description
1	MODE pin	Power down by driving MODE pin to low
2	SERIF	Power down by SERIF writing 0h to register 20h bit <0>
3	Low Battery	Power down if VBAT is lower than the supervisor off-threshold
4	VNEG CP OVC	Power down if VNEG is higher than the VNEG off-threshold

8.5.3 Start-up Sequence

The start-up sequence depends on the used mode.

In stand-alone mode the sequence runs automatically, in I2C mode the sequence runs till a defined state and waits then for an I2C command. Either the automatic sequence is started by setting the CONT_PWRUP bit in addition to the PWR_HOLD bit. If only the PWR_HOLD is set all enable bits for headphone, microphone, etc have to be set manually.

Figure 20. Stand-Alone Mode Start-Up Sequence

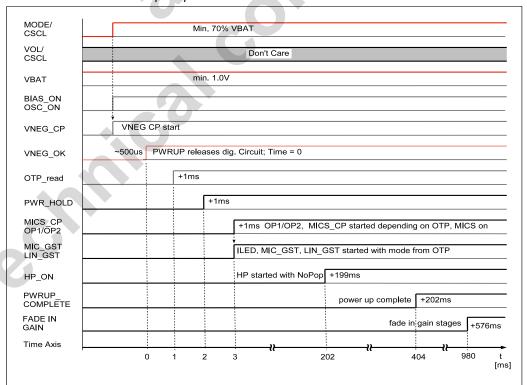
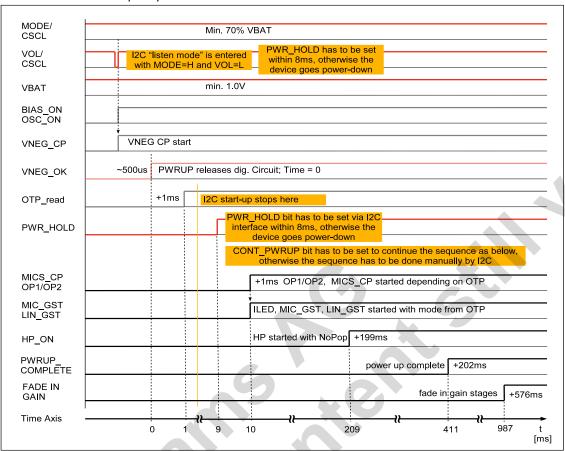




Figure 21. I2C Mode Start-Up Sequence



8.5.4 Mode Switching

When the chip in stand-alone mode (no I2C control) the mode can be switched with different levels on the MODE pin. *Table 10. Operation Modes*

MODE	MODE pin	Description
OFF	LOW (VNEG)	Chip is turned off
ANC	HIGH (VBAT)	Chip is turned on and active noise cancellation is active
MONITOR	TRI-STATE (VBAT/2)	Chip is turned on and monitor mode is active In Monitor mode a different (normally higher) microphone preamplifier gain can be chosen to get an amplification of the surrounding noise. This volume can be either fixed or be controlled by the VOL input. To get rid of the low pass filtering needed for the noise cancellation, the headphone input multiplexer can be set to a different (normally to MIC) source. In addition the LineIn gain can be lowered to reduce the loudness of the music currently played back.

In I2C mode the monitor mode can be activated be setting the corresponding bit in the system register.

8.5.5 Status Indication

AS3501 and AS3502 feature a on-status information via the current output pin ILED. The current can be controlled in 3 steps and be switched off, by setting the PWM accordingly (0%, 25%, 50% and 100% duty cycle of a 50kHz PWM signal).

If LOW_BAT (typ. 0.9V) is active, ILED switches to blinking with 1Hz, 50% duty cycle and 50% current setting.



8.6 VNEG Charge Pump

8.6.1 General

The VNEG charge pump uses one external 1uF capacitor to generate a negative supply voltage out of the battery input voltage to supply all audio related blocks. This allows a true-ground headphone output with no more need of external dc-decoupling capacitors.

8.6.2 Parameter

VBAT=1.5V, T_A= 25°C, unless otherwise mentioned

Table 11. Headphone Output Parameter

Symbol	Parameter	Condition	Min	Тур	Max	Unit
V _{IN}	input voltage	VBAT	1.0	1.5	1.8	V
V _{OUT}	output voltage	VNEG	-0.7	-1.5	-1.8	V
C _{EXT}	external flying capacitor			1		uF

8.7 OTP Memory & Internal Registers

8.7.1 General

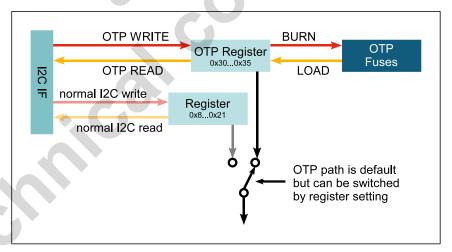
The OTP memory consists of OTP register and the OTP fuses. The OTP register can be written as often as wanted but will lose the content on power off. The OTP fuses are intended to store basic chip configurations as well as the microphone gain settings to optimize the ANC performance and get rid of sensitivity variations of different microphones. Burning the fuses can only be once and is a permanent change, which means the fuses keep the content even if the chip is powered down.

When the chip is controlled by a microcontroller via I2C, the OTP memory don't has to be used.

8.7.2 Register & OTP Memory configuration

The following graphics is showing the principal register interaction.

Figure 22. Register Access



Registers 0x8, 0x9, 0xA, 0xB, 0xC and 0x21 have only effect when the corresponding "REG_ON" bit is set, otherwise the chip operates with the OTP Register settings which are loaded from the OTP fuses at every start-up.



All registers settings can be changed several times, but will loose the content on power off. When using the I2C mode the chip configuration has to be loaded from the microcontroller after every start-up. In stand alone mode the OTP fuses have to be programmed for a permanent change of the chip configuration.

A single OTP cell can be programmed only once. Per default, the cell is "0"; a programmed cell will contain a "1". While it is not possible to reset a programmed bit from "1" to "0", multiple OTP writes are possible, but only additional unprogrammed "0"-bits can be programmed to "1".

Independent of the OTP programming, it is possible to overwrite the OTP register temporarily with an OTP write command at any time. This setting will be cleared and overwritten with the hard programmed OTP settings at each power-up sequence or by a LOAD operation.

The OTP memory can be accessed in the following ways:

LOAD Operation:

The LOAD operation reads the OTP fuses and loads the contents into the OTP register. A LOAD operation is automatically executed after each power-on-reset.

WRITE Operation:

The WRITE operation allows a temporary modification of the OTP register. It does not program the OTP. This operation can be invoked multiple times and will remain set while the chip is supplied with power and while the OTP register is not modified with another WRITE or LOAD operation.

READ Operation:

The READ operation reads the contents of the OTP register, for example to verify a WRITE command or to read the OTP memory after a LOAD command.

BURN Operation:

The BURN operation programs the contents of the OTP register permanently into the OTP fuses. Don't use old or nearly empty batteries for burning the fuses.

Attention: If you once burn the OTP_LOCK bit no further programming, e.g. setting additional "0" to "1", of the OTP can be done.

For production the OTP_LOCK bit must be set to avoid an unwanted change of the OTP content during the lifetime of the product.

8.7.3 OTP fuse burning

In most stand alone applications the I2C pins are not accessible. Burning the fuses can be done by switching the line inputs into a special mode to access the chip by I2C over the line input connections. This allows trimming of the microphone gain with no openings in the final housing and so no influence to the acoustic of the headset.

This mode is called "Application Trim" mode, or short "APT". (Patent Pending)

During the application trim mode LINR has to provide the clock, while LINL has to provide the data for the I2C communication.

Please note that the OTP register cannot be accessed directly but have to be enabled before a read or write access. This is independent whether you access the OTP register via the normal I2C pins or in application trim mode via LINL and LINR. Please refer to the detailed register description to get more information on how the registers can be accessed.

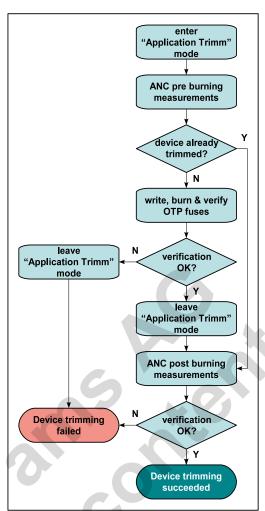
To achieve a proper burning of the fuses, the negative supply has to be buffered by applying an external negative supply during burning. This voltage can also be applied to the LINL terminal. An internal switch is connecting LINL and VNEG during the fuse burning. LINR has to provide the clock for burning the fuses.

The below flow chart shows the principle steps of the OTP burning process. The application trim mode can only be entered once. There is no possibility to stop the sequence, exit and re-enter the application trim mode to make e.g. the verification in a second step. The OTP bring sequence has to be done as shown in the flow chart.

A more detailed description of the individual steps is available in an application note.



Figure 23. OTP Burning Process





8.8 2-Wire-Serial Control Interface

8.8.1 General

There is an I2C slave block implemented to have access to 64 byte of setting information.

The I2C address is: Adr_Group8 - audio processors

- 8Eh_write
- 8Fh_read

8.8.2 Protocol

Table 12. 2-Wire Serial Symbol Definition

Symbol	Definition	RW	Note
S	Start condition after stop	R	1 bit
Sr	Repeated start	R	1 bit
DW	Device address for write	R	1000 1110b (8Eh)
DR	Device address for read	R	1000 1111b (8Fh)
WA	Word address	R	8 bit
А	Acknowledge	W	1 bit
N	No Acknowledge	R	1 bit
reg_data	Register data/write	R	8 bit
data (n)	Register data/read	W	8 bit
Р	Stop condition	R	1 bit
WA++	Increment word address internally	R	during acknowledge
	AS3501 AS3502 (=slave) receives data		
	AS3501 AS3502 (=slave) transmits data		·

Figure 24. Byte Write

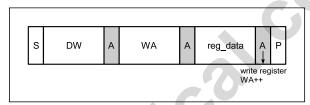
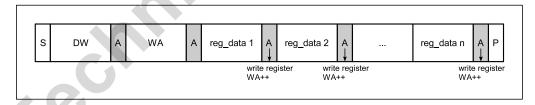


Figure 25. Page Write



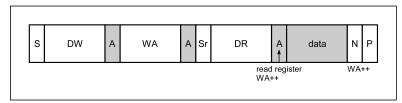
Byte Write and Page Write formats are used to write data to the slave.

The transmission begins with the START condition, which is generated by the master when the bus is in IDLE state (the bus is free). The device-write address is followed by the word address. After the word address any number of data bytes can be sent to the slave. The word address is incremented internally, in order to write subsequent data bytes on subsequent address locations.



For reading data from the slave device, the master has to change the transfer direction. This can be done either with a repeated START condition followed by the device-read address, or simply with a new transmission START followed by the device-read address, when the bus is in IDLE state. The device-read address is always followed by the 1st register byte transmitted from the slave. In Read Mode any number of subsequent register bytes can be read from the slave. The word address is incremented internally.

Figure 26. Random Read

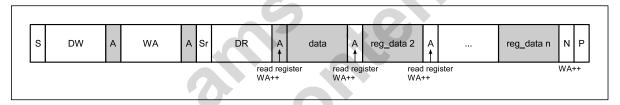


Random Read and Sequential Read are combined formats. The repeated START condition is used to change the direction after the data transfer from the master.

The word address transfer is initiated with a START condition issued by the master while the bus is idle. The START condition is followed by the device-write address and the word address.

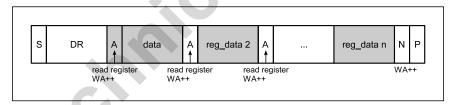
In order to change the data direction a repeated START condition is issued on the 1st SCL pulse after the acknowledge bit of the word address transfer. After the reception of the device-read address, the slave becomes the transmitter. In this state the slave transmits register data located by the previous received word address vector. The master responds to the data byte with a not-acknowledge, and issues a STOP condition on the bus.

Figure 27. Sequential Read



Sequential Read is the extended form of Random Read, as more than one register-data bytes are transferred subsequently. In difference to the Random Read, for a sequential read the transferred register-data bytes are responded by an acknowledge from the master. The number of data bytes transferred in one sequence is unlimited (consider the behavior of the word-address counter). To terminate the transmission the master has to send a not-acknowledge following the last data byte and generate the STOP condition subsequently.

Figure 28. Current Address Read

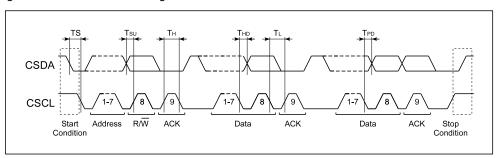


To keep the access time as small as possible, this format allows a read access without the word address transfer in advance to the data transfer. The bus is idle and the master issues a START condition followed by the Device-Read address. Analogous to Random Read, a single byte transfer is terminated with a not-acknowledge after the 1st register byte. Analogous to Sequential Read an unlimited number of data bytes can be transferred, where the data bytes has to be responded with an acknowledge from the master. For termination of the transmission the master sends a not-acknowledge following the last data byte and a subsequent STOP condition.



8.8.3 Parameter

Figure 29. 2-Wire Serial Timing



VBAT >=1.4V, T_{amb}=25°C; unless otherwise specified

Table 13. 2-Wire Serial Parameter

Symbol	Parameter	Condition	Min	Тур	Max	Unit
V _{CSL}	CSCL, CSDA Low Input Level	(max 30%VBAT)	0	(-)	0.42	V
V _{CSH}	CSCL, CSDA High Input Level	CSCL, CSDA (min 70%VBAT)	0.98	-		٧
HYST	CSCL, CSDA Input Hysteresis		200	450	800	mV
V _{OL}	CSDA Low Output Level	at 3mA	-	-	0.4	٧
Tsp	Spike insensitivity		50	100	-	ns
T _H	Clock high time	max. 400kHz clock speed	500			ns
TL	Clock low time	Clock low time max. 400kHz clock speed				ns
T _{SU}	7	CSDA has to change Tsetup before rising edge of CSCL	250	-	-	ns
T _{HD}		No hold time needed for CSDA relative to rising edge of CSCL	0	-	-	ns
TS		CSDA H hold time relative to CSDA edge for start/stop/rep_start	200	-	-	ns
T _{PD}	-9	CSDA prop delay relative to low going edge of CSCL		50		ns

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9 Register Description

Table 14. I2C Register Overview

Addr	Name	b7	b6	b5	b4	b3	b2	b1	b0		
Audio Re	Audio Registers										
00-07h	reserved										
08h	MIC_L	MIC_MODE 0: StereoSingleEnd 1: MonoDiff	MICL_VOL<6:0> Gain from MICL	MICL_VOL<6:0> Gain from MICL to QMICL or Mixer = -6dB+41.6dB; 127 steps of 0.375dB							
09h	MIC_R	MIC_REG_ON 0: use reg 30h & 31h 1: use reg 08h & 09h	MICR_VOL<6:0: Gain from MICR	> to QMICR or Mix	er = -6dB+41.6	dB; 127 steps of	0.375dB				
0Ah	LINE_IN	LIN_REG_ON 0: use reg 33h and VOL pin 1: use reg 0Ah	LIN_MODE 0: StereoSingleEnd 1: MonoDiff	StereoSingleEnd 0: MUTE;							
0Bh	GP_OP_L	HP_MUX<1:0> 0: MIC; 1: OP1; 2: OP2; 3: open		OP2L<3:0> 0: OP2L inverting mo 0x10xF: OP2L non		010.5dB; 15 steps o	of 0.75dB	OP2L_ON	OP1L_ON		
0Ch	GP_OP_R	OP_REG_ON 0: use reg 34h 1: use reg 0Bh & 0Ch	HP_MODE 0: StereoSingleEnd 1: MonoDiff	OP2R<3:0> 0: OP2R inverting mo 0x10xF: OP2R non		010.5dB; 15 steps of	of 0.75dB	OP2R_ON	OP1R_ON		
0Dh-1Fh	reserved										
System F	Register										
20h	SYSTEM	Design_Version<	3:0>			REG3F_ON	MONITOR_ON	CONT_PWRUP	PWR_HOLD		
PWR REG ON ILED<1:0>				HP_ON	MIC_ON	LIN_ON	MICS_CP_ON	MICS_ON			
			LOW_BAT	PWRUP_ COMPLETE	(5)						
22h-2Fh	reserved						•				



Table 14. I2C Register Overview

Addr	Name	b7	b6	b5	b4	b3	b2	b1	b0		
OTP Reg	OTP Register										
30h	ANC_L	TEST_BIT_1		MICL_VOL_OTP<6:0> Gain from MICL to QMICL or Mixer = -6dB+41.6dB; 127 steps of 0.375dB							
31h	ANC_R	TEST_BIT_2	MICR_VOL_OTI Gain from MICR		er = -6dB+41.6	dB; 127 steps of 0).375dB	10			
32h	MIC_MON	MON_MODE 0: fixed volume 1: adj. volume	Gain from MICI/F	IIC_MON_OTP<6:0> sain from MICI/R to QMICL/R or Mixer = -6dB+41.6dB; 0.375dB steps, if MON_MODE is set to 0 sain from MICI/R to QMICL/R or Mixer = -6dB+41.6dB; 0.375dB steps, adjustable by VOL pin if MON_MODE is set to							
33h	AUDIO_SET	VOL_PIN_OFF	VOL_PIN_ MODE 0: potentiometer 1: up/down button	OTP 0: StereoSingleEnd 1: MonoDiff	MIC_MODE_ OTP 0: StereoSingleEnd 1: MonoDiff	HP_MODE_ OTP 0: StereoSingleEnd 1: MonoDiff	LIN_MON_ATTEN<2:0> 0: no attenuation; 16: LIN_VOL<6:0> shift by -6dB36dB 7: MUTE				
34h	GP_OP	HP_MUX_OTP< 0: MIC; 1: OP1; 2: OP2; 3: -	1:0>	OP2_OTP<3:0> 0: OP2 inverting mod 0x10xF: OP2 non in	de;	10.5dB; 15 steps of 0).75dB	OP2_ON_OTP	OP1_ON_OT P		
35h	OTP_SYS	OTP_LOCK 0: write reg 30h 35h 1: lock reg 30h35h	TEST_BIT_5	MON_HP_MUX- 0: MIC; 1: OP1; 2: OP2; 3: -	<1:0>	ILED_OTP<1:0> 0: OFF; 1: 25%; 2: 50%; 3: 100%	•	MICS_CP_OFF	I2C_MODE		
36h-3Dh	reserved				7						
3Eh	CONFIG_1					EXTBURNCLK					
3Fh	CONFIG_2				BURNSW	TM_REG34-35	TM_REG30-33	OTP_MODE<1:0 0: READ; 1: LOAD; 2: WRITE; 3: BURN)>		



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Data Sheet - Register Description



Table 15. MIC_L Register

	Name			Base	Default
	MIC_L			2-wire serial	00h
				Left Microphone Inp	ut Register
-			•	the left microphone inpuegister is reset at POR.	t and defines the microphone
Bit	Bit Name	Default	Access	E	Bit Description
7	MIC_MODE	0	R/W	Selects the microphone 0: single ended stereo 1: mono differential mod	mode
6:0	MICL_VOL<6:0>	000 0000	R/W	Volume settings for left steps of 0.375dB 00 0000: MUTE 00 0001: -5.625dB gain 00 0010: -5.25 dB gain 11 1110: 41.250dB gain 11 1111: 41.625 dB gain	

Table 16. MIC_R Register

	Name			Base Default
	MIC_R			2-wire serial 00h
				Right Microphone Input Register
	Offset: 09h Configures the configuration that configures the configuration that configures the configuration that configuration the configuration that configures the configuration that configuration			the right microphone input and enables register 08h & 09h. POR.
Bit	Bit Name	Default	Access	Bit Description
7	MIC_REG_ON	0	R/W	Defines which registers are used for the microphone settings. 0:settings of register 30h and 31h are used 1: settings of register 08h and 09h are used
6:0	MICR_VOL<6:0>	000 0000	R/W	Volume settings for right microphone input, adjustable in 127 steps of 0.375dB 00 0000: MUTE 00 0001: -5.625dB gain 00 0010: -5.25 dB gain 11 1110: 41.250dB gain 11 1111: 41.625 dB gain



Table 17. LINE_IN Register

Name				Base	Default	
	LINE_IN			2-wire serial 00h		
				Line Input Re	gister	
	Offset: 0Ah	•		tion for the line input, def Γhis register is reset at P	ines the line input operation mode and OR.	
Bit	Bit Name	Default	Access	E	Bit Description	
7	LIN_REG_ON	0	R/W	Defines which source is used for the line input settings. 0: settings of register 33h and VOL pin are used 1: register 0Ah is used		
6	LIN_MODE	0	R/W	Selects the line input mo 0: single ended stereo 1: mono differential mod	mode	
5:0	LIN_VOL<5:0>	00 0000	R/W	Volume settings for line 00 0000: MUTE 00 0001:-46.5dB gain 00 0010:-45.75dB dain 11 1110:-0.75dB gain 11 1111:.0 dB gain	input, adjustable in 63 steps of 0.75dB	

Table 18. GP_OP_L Register

Name				Base	Default
	GP_OP_L			2-wire serial	00h
			Left Ge	neral Purpose Operation	onal Amplifier Register
	Offset: 0Bh			stages, defines opamp 2 er is reset at POR.	2 mode and gain and sets the HP input
Bit	Bit Name	Default	Access		Bit Description
7:6	HP_MUX<1:0>	00	R/W	Multiplexes the analog 00: MIC: selects QMIC 01: OP1: selects QOP1 10:OP2: selects QOP2I 11: open: no signal mix	L/R output L/R outputs
5:2	OP2L<3:0>	0000	R/W	Mode and volume settir of 0.75dB 0000: OP2L in invertir 0001: 0 dB gain, OP2L 0001: 0.75 dB gain, nor , 1110: 9.75dB gain, non 1111:.10.5 dB gain, non	in non inverting mode n inverting inverting
1	OP2L_ON	0	R/W	Enables left OP 2 0: left OP2 is switched 1: left OP2 is enabled	d off
0	OP1L_ON	0	R/W	Enables left OP 1 0: left OP1 is switched 1: left OP1 is enabled	d off



Table 19. GP_OP_R Register

Name				Base Default			
	GP_OP_R			2-wire serial 00h			
			Right Ge	eneral Purpose Operation	onal Amplifier Register		
	Offset: 0Ch		bles the right opamp stages, defines opamp 2 mode and gain and sets the HP le. This register is reset at POR.				
Bit	Bit Name	Default	Access	E	Bit Description		
7	OP_REG_ON	0	R/W	Defines which register is used for the opamp and HP settings 0: settings of register 33h and 34h are used 1: register 0B and 0Ch are used			
6	HP_MODE	0	R/W	Selects the line input mode 0: single ended stereo mode 1: mono differential mode			
5:2	OP2R<3:0>	0000	R/W	Mode and volume setting steps of 0.75dB 0000: OP2R in inverting 0001: 0 dB gain, OP2R 0001: 0.75 dB gain, nonun, 1110: 9.75dB gain, nonun 1111:.10.5 dB gain, nonun	in non inverting mode inverting inverting		
1	OP2R_ON	0	R/W	Enables right OP 2 0: right OP2 is switched off 1: right OP2 is enabled			
0	OP1R_ON	0	R/W	Enables right OP 1 0: right OP1 is switche 1: right OP1 is enabled	ed off		

Table 20. SYSTEM Register

Name				Base	Default
	SYSTEM			2-wire serial	31h
	Offset: 20h			SYSTEM Reg	ister
	Oliset. 2011	This register	is reset at	a POR.	
Bit	Bit Name	Default	Access		Bit Description
7:4	Design_Version<3:0>	0011	R	AFE number to identify the design version 0011: for chip version 1v2	
3	TESTREG_ON	0	R/W	o: normal operation enables writing to test register 3Eh & 3Fh to configure the OTP and set the access mode.	
2	MONITOR_ON	0	R/W	Enables the monitor mo 0: normal operation 1: monitor mode enable	
1	CONT_PWRUP	0	R/W	Continues the automatic power-up sequence when using the I2C mode 0: chip stops the power-up sequence after the supplies are stable, switching on individual blocks has to be don via I2C commands 1: automatic power-up sequence is continued	
0	PWR_HOLD	1	R/W	0: power up hold is clea 1: is automatically set	red and AFE will power down to on after power on



Table 21. PWR_SET Register

Name				Base Default		
PWR_SET				2-wire serial 0x11 1111b (stand alone mode) 0x00 0000b (I2C mode)		
			•	Power Setting R	Register	
	Offset: 21h	correspondi	ng block	re that writing to this register will enable/disable the blocks, while reading gets the actual status. It is not possible g ILED settings. This register is reset at POR.		
Bit	Bit Name	Default	Access	ı	Bit Description	
7	PWR_REG_ON	0	R/W	Defines which register is 0: all blocks stay on a 1: register 21h is used	s used for the power settings. s defined in the start-up sequence	
6:5	ILED<1:0>	00	W	Sets the current sunk in 00: current sink switch 01: 25% 10: 50% 11: 100%		
6	LOW_BAT	х	R	VBAT supervisor status 0: VBAT is above brov 1: BVDD has reached b	vn out level	
5	PWRUP_COMPLETE	х	R	Power-Up sequencer st 0: power-up sequence 1: power-up sequence	incomplete	
4	HP_ON	0	W	0: switches HP stage of 1: switches HP stage or		
		Х	R	0: HP stage not power 1: normal operation	red	
3	MIC_ON	0	W	0: switches microphore 1: switches microphone		
		X	R	0: microphone stage r 1: normal operation	not powered	
2	LIN_ON	0	W	0: switches line input 1: switches line input sta		
		×	R	0: line input stage not 1: normal operation	powered	
1	MICS_CP_ON	0	W	W 0: switches microphone supply charge pump off 1: switches microphone supply charge pump on		
		х	R	R 0: microphone supply charge pump not powered 1: normal operation		
0	MICS_ON	0	W	0: switches microphore 1: switches microphone		
		Х	R	0: microphone supply 1: normal operation	not enabled	



Table 22. ANC_L Register

Name				Base	Default
ANC_L				2-wire serial	80h (OTP)
			Left OTP Microphone I	nput Register	
needs to be ena			enabled by		t. This is a special register, writing first. This register is reset at POR and
Bit	Bit Name	Default	Access	Bit Description	
7	TEST_BIT1	1	R	for testing purpose only	. 9.
6:0	MICL_VOL_OTP <6:0>	000 0000	R/W	Volume settings for left steps of 0.375dB 00 0000: MUTE 00 0001: -5.625dB gain 00 0010: -5.25 dB gain 11 1110: 41.250dB gain 11 1111: 41.625 dB gain	

Table 23. ANC_R Register

	Name			Base	Default
ANC_R				2-wire serial	80h (OTP)
				Right OTP Microphone	Input Register
needs to be ena			enabled by		t. This is a special register, writing first. This register is reset at POR and
Bit	Bit Name	Default	Access	E	Bit Description
7	TEST_BIT2	1	R	for testing purpose only	
6:0	MICR_VOL_OTP <6:0>	000 0000	R/W	Volume settings for right steps of 0.375dB 00 0000: MUTE 00 0001: -5.625dB gain 00 0010: -5.25 dB gain 11 1110: 41.250dB gain 11 1111: 41.625 dB gain	



Table 24. MIC_MON Register

Name				Base	Default
MIC_MON				2-wire serial	00h (OTP)
		O	PT Microphone Monito	r Mode Register	
register, writing			ing needs		monitor mode. This is a special 10b to Reg 3Fh first. This register is e contents.
Bit	Bit Name	Default	Access	E	Bit Description
7	MON_MODE	0	R/W		rking with fixed microphone gain djustable gain via the VOL pin
6:0	MIC_MON_OTP <6:0>	000 0000	R/W	adjustable in 127 steps	

Table 25. AUDIO_SET Register

	Name			Base Default		
	AUDIO_SET			2-wire serial	00h (OTP)	
				OPT Audio Setting	g Register	
	Offset: 33h		b to Reg 3	udio settings. This is a special register, writing needs to be enabled Reg 3Fh first. This register is reset at POR and gets loaded with the its.		
Bit	Bit Name	Default	Access		Bit Description	
7	VOL_PIN_OFF	0	R/W	0: VOL pin is enabled 1: line in volume setting VOL_PIN_MODE has to	s can only be done via I2C. to be set to 1 in this mode.	
6	VOL_PIN_MODE	0	R/W	0: VOL pin is in potentiometer mode 1: VOL pin is in up/down button mode		
5	LIN_MODE_OTP	0	R/W	0: line input stage ope 1: line input operating in	eating in single ended mode n mono balanced	
4	MIC_MODE_OTP	0	R/W	0: microphone input s 1: normal operating in n	tage opeating in single ended mode nono balanced	
3	HP_MODE_OTP	0	R/W	0: headphone stage of 1: normal operating in n	peating in single ended mode nono balanced	
2:0	LIN_MON_ATTEN <6:0>	000	R/W	Volume settings for line in 7 steps of 6dB and m 000: 0dB gain 001: -6dB gain 110: -36dB gain 111: MUTE	input during monitor mode, adjustable ute.	



Table 26. GP_OP Register

Name				Base	Default		
	GP_OP	2-wire serial 00h (OTP)					
			OTP Ge	neral Purpose Operation	nal Amplifier Register		
	Offset: 34h	Enables the opamp stages, defines opamp 2 mode and gain and sets the HP input multiplexer. This is a special register, writing needs to be enabled by writing 10b to Reg 3Fh first. This register is reset at POR and gets loaded with the OTP fuse contents.					
Bit	Bit Name	Default	Access	E	Bit Description		
7:6	HP_MUX_OTP<1:0>	00	R/W	Multiplexes the analog a 00: MIC: selects QMIC 01:OP1: selects QOP1L 10:OP2: selects QOP2L 11: open: no signal mixe	L/R output /R outputs		
5:2	OP2_OTP<3:0>	0000	R/W	Mode and volume settings for OP2, adjustable in 15 steps of 0.75dB 0000: OP2L in inverting mode 0001: 0 dB gain, OP2L in non inverting mode 0001: 0.75 dB gain, non inverting, 1110: 9.75dB gain, non inverting 1111: 10.5 dB gain, non inverting			
1	OP2_ON	0	R/W	0: OP2 is switched off 1: left OP2 is enabled			
0	OPL_ON	0	R/W	0: OP1 is switched off 1: OP1 is enabled			

Table 27. OTP_SYS Register

	Name			Base	Default
	OTP_SYS			2-wire serial	40h (OTP)
				OTP System Setting	gs Register
				y writing 10b to Reg 3Fh	ion. This is a special register, writing first. This register is reset at POR and
Bit	Bit Name	Default	Access	E	Bit Description
7	OTP_LOCK	0	R/W	0: additional bits can be fused inside the OTP 1: OTP fusing gets locked, no more changes can be done	
6	TEST_BIT5	1	R	for testing purpose only	
5:4	MON_HP_MUX <1:0>	00	R/W	Multiplexes the analog audio signal to HP amp in monitor mode 00: MIC: selects QMICL/R output 01: OP1: selects QOP1L/R outputs 10:OP2: selects QOP2L/R output 11: open: no signal mixed together with the line input signal	
3:2	ILED_OTP<1:0>	00	W	Sets the current sunk in 00: current sink switch 01: 25% 10: 50% 11: 100%	



Table 27. OTP_SYS Register

Name				Base	Default
	OTP_SYS			2-wire serial	40h (OTP)
				OTP System Setting	gs Register
	Offset: 35h	Defines several system settings for OTP operation. The needs to be enabled by writing 10b to Reg 3Fh first. Togets loaded with the OTP fuse contents.			
Bit	Bit Name	Default	Access	E	Bit Description
1	MICS_CP_OFF	0	R/W	0: MICS charge pump 1: MICS charge pump is	
0	I2C	0	R/W	0: I2C and stand alone 1: chip starts-up in I2C i	e mode start-up possible mode only

Table 28. CONFIG_1 Register

	Name			Base	Default
	CONFIG_1			2-wire serial	00h
				OTP Configuration	Register
	Offset: 3Eh Controls the clock configuration. This is a special register, writing needs to by writing 9h to Reg 20h first. This register is reset at POR and gets loade OTP fuse contents.				
Bit	Bit Name	Default	Access		Bit Description
7:4	-	0000	n/a	M . (3)	
3	EXTBURNCLK	0	0 n/a 0: ext. clock for OTP burning disabled 1: ext. clock for OTP burning enabled		
2:0	-	000	n/a		

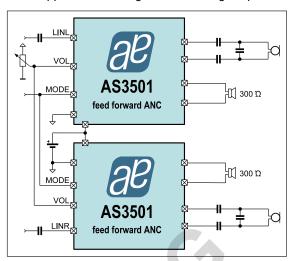
Table 29. CONFIG_2 Register

Name				Base	Default	
	CONFIG_2			2-wire serial	00h	
				OTP Access Configura	ation Register	
Oliset, si ii			Reg 20h fi	P access. This is a special register, writing needs to be enabled by 20h first. This register is reset at POR and gets loaded with the OTP		
Bit	Bit Name	Default	Access	E	Bit Description	
7:5	-	000	n/a			
4	BURNSW	0	n/a	0: BURN switch from I 1: BURN switch from LI	LINL to VNEG is disabled NL to VNEG is enabled	
3	TM_REG34-35	0	n/a	0: test mode for Register 1: test mode for Register		
2	TM_REG30-33	0	n/a	0: test mode for Register 1: test mode for Register		
1:0	OTP_MODE<1:0>	00	R/W	Controls the OTP acces 00: READ 01: LOAD 10: WRITE 11: BURN	es	



10 Application Information

Figure 30. AS3501 High Performance Application in Bridged Mode for high impedance headsets



For high impedance headphones two AS3501 can be used in a bridged mode each one driving one side of the headphone load as differential output to get 24mW output power per channel. Also the microphone inputs can be used in differential mode to reduce the noise level.

Figure 31. AS3502 on Music Player with ANC

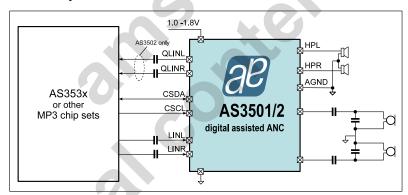




Figure 32. AS3501 feed-forward application example

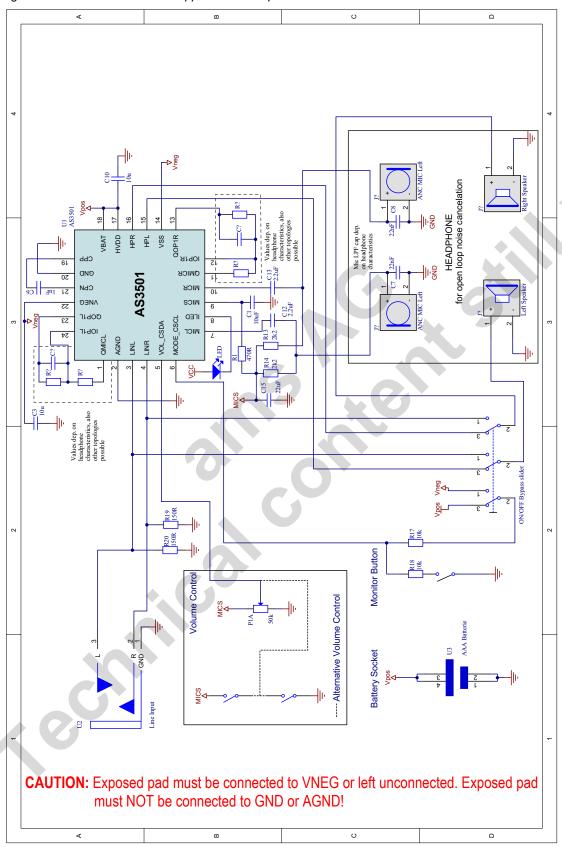




Figure 33. AS3502 feed-back application example

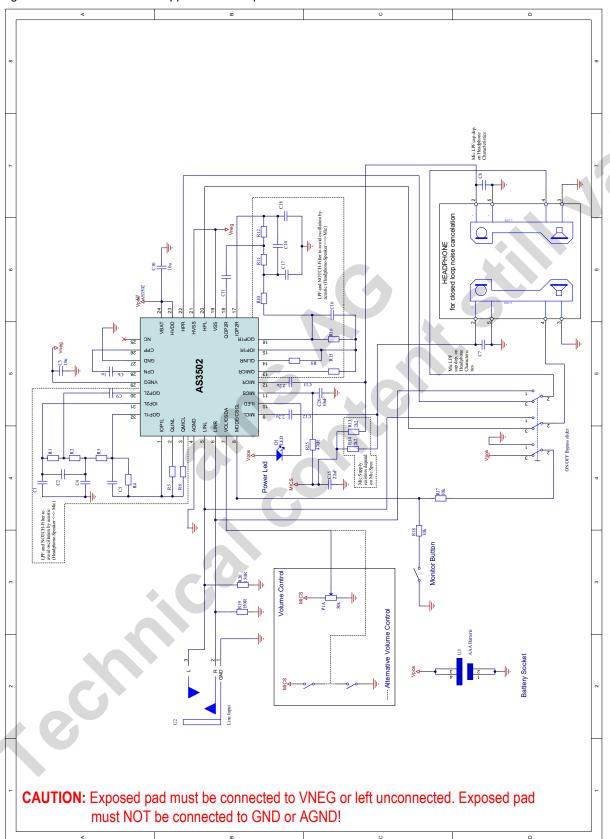
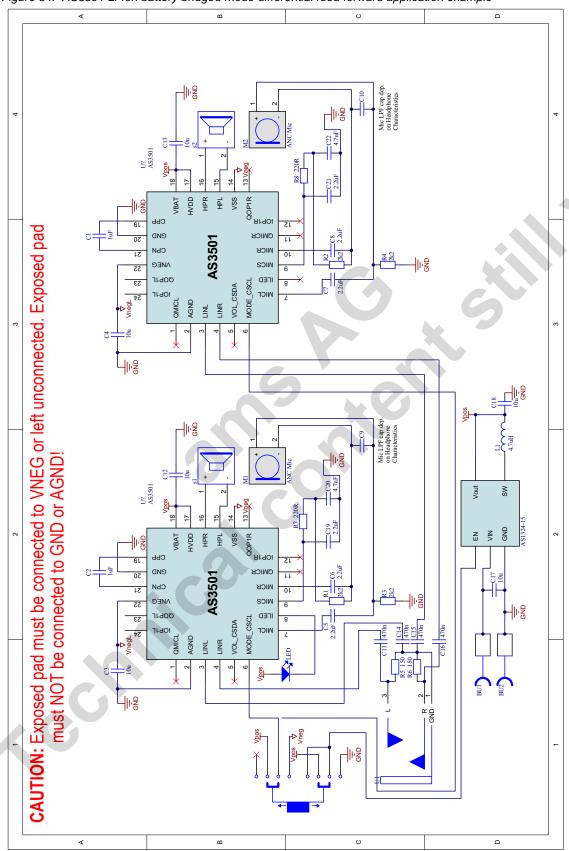




Figure 34. AS3501 Li-lon battery bridged mode differential feed forward application example





11 Package Drawings and Markings

Figure 35. QFN Marking

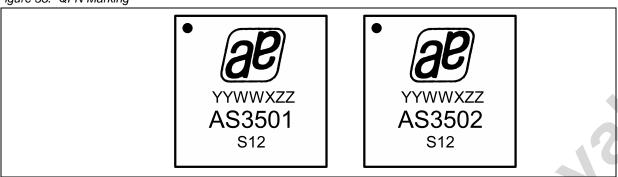


Table 30. Package Code YYWWXZZ

YY	ww	X	ZZ
last two digits of the year	manufacturing week	plant identifier	free choice / traceability code



Figure 36. AS3501 QFN24 0.5mm pitch

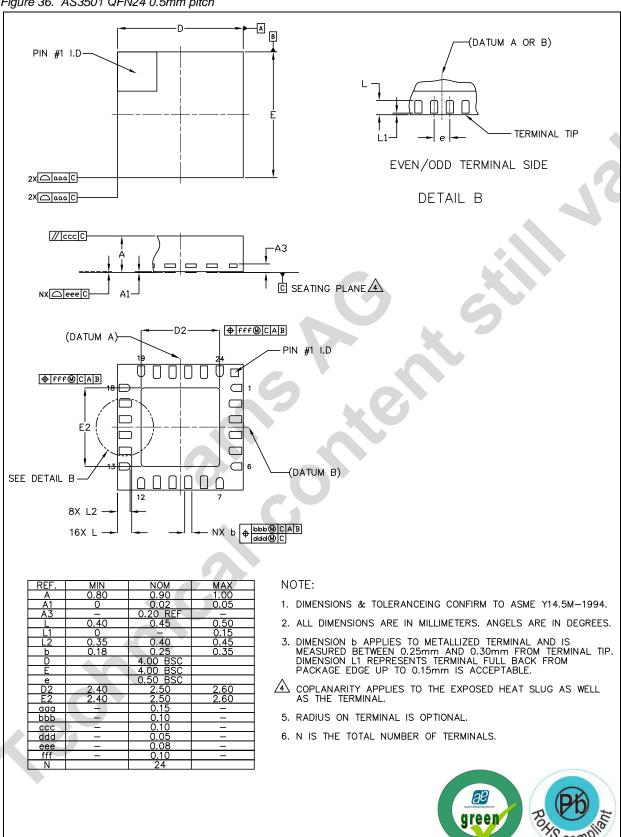
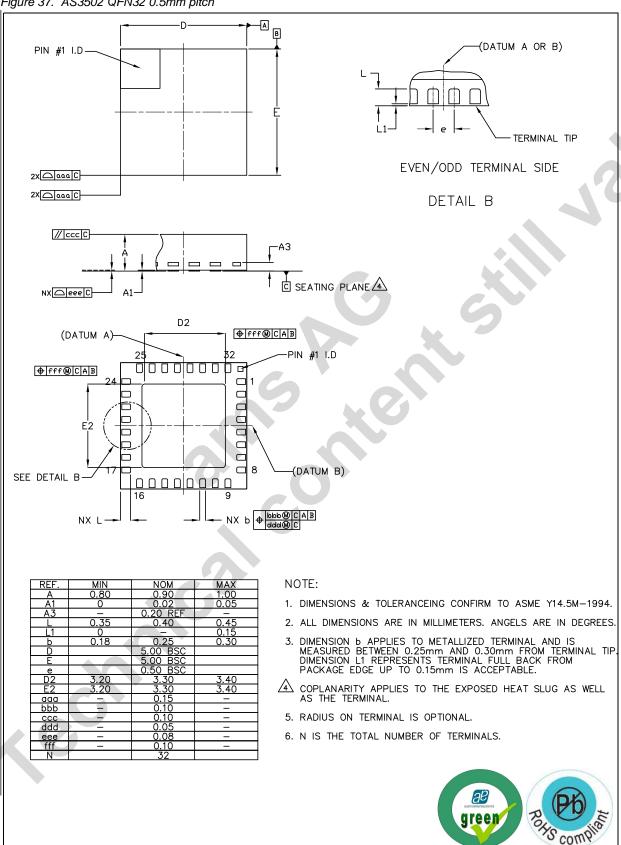




Figure 37. AS3502 QFN32 0.5mm pitch





12 Ordering Information

The devices are available as the standard products shown in Table 31.

Table 31. Ordering Information

Ordering Code	Description	Delivery Form	Package
AS3501-EQFP	Low Power Ambient Noise-Cancelling Speaker Driver	•	QFN 24 [4.0x4.0x0.85mm] 0.5mm pitch
AS3502-EQFP	Low Power Ambient Noise-Cancelling Speaker Driver	•	QFN 32 [5.0x5.0x0.85mm] 0.5mm pitch

Note: All products are RoHS compliant and austriamicrosystems green.

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Revision History

Table 32. Revision History

Revision	Date	Owner	Description	
1.0	18.5.2009	pkm	official release	
1.01	5.6.2009	pkm	updated application schematics	
1.02	15.7.2009	pkm	typo correction	
1.1	19.1.2009	pkm	updated pin and pinout description	
1.11	03.8.2010	hgt	updated solder profile, power up sequences and block diagrams	
1.12	09.6.2011	hgt	updated order information and electrical characteristics	
1.13	06.07.2011	hgt	updated package information, operating conditions, absolute maximum ratings and order information	

Note: Typos may not be explicitly mentioned under revision history.



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